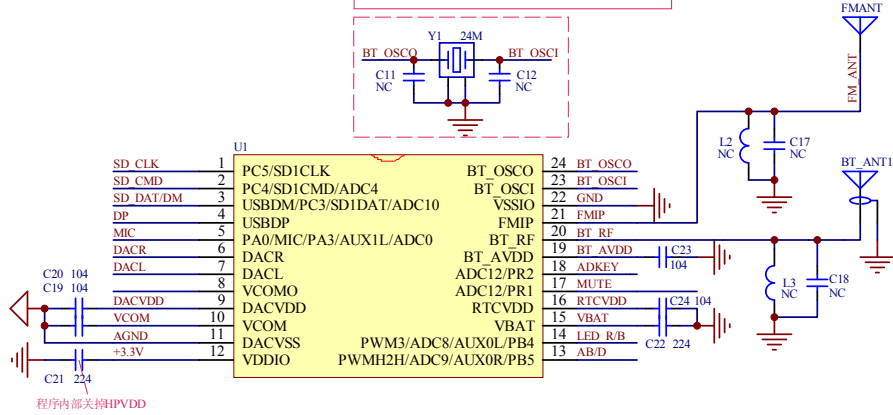
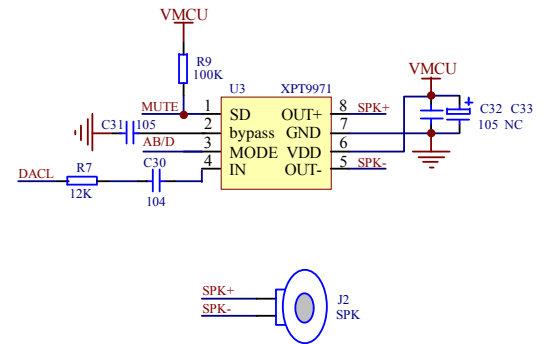
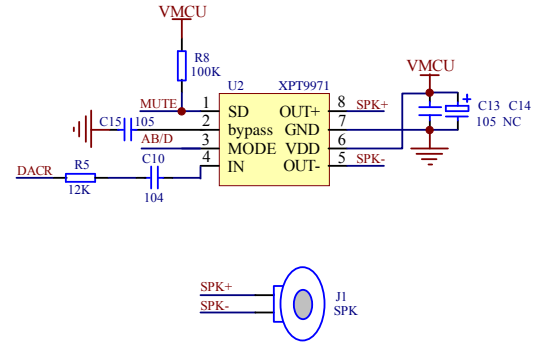


注：原理图中注释说明设计时需特别注意

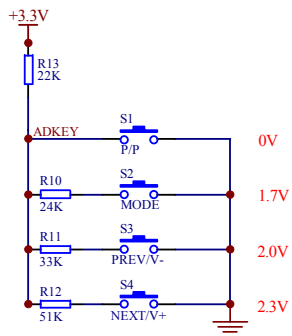
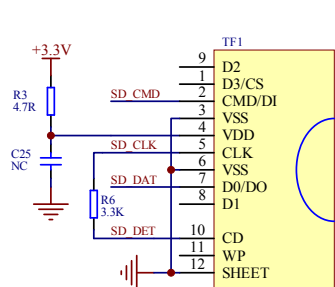
晶振选型：
封装：可兼容3225, M49S, HC49S等不同封装
要求：稳定性、一致性要好，频偏偏差：±10PPM以内
电容：晶振匹配电容位置请预留



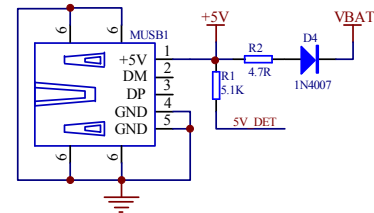
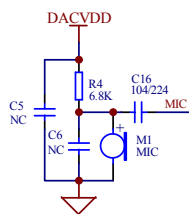
MCU



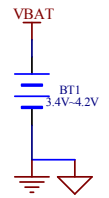
PA



TF、LED、Mic



yunThinker 云信通讯
硬件部 刘工



POWER

GND、AGND在电源入口处短接在一起！